TVS Diode

Transient Voltage Suppressor Diodes

ESD24VL1B Series

Low Capacitance Bi-directional ESD / Transient Protection Diode

ESD24VL1B-02LS
ESD24VL1B-02LRH

Data Sheet

Revision 1.1, 2012-05-04
Final

Power Management & Multimarket

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Revision History: Rev. 1.0, 2011-12-06	
Page or Item	**Subjects (major changes since previous revision)**
Revision 1.1, 2012-05-04	
7 + 8	ESD air and contact discharge change
8	Parameter V_{BR} inserted in **Table 3-2**

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Last Trademarks Update 2010-10-26

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1 Low Capacitance Bi-directional ESD / Transient Protection Diode

1.1 Features

- ESD / transient protection according to:
  - IEC61000-4-2 (ESD): ±20 kV (air), ±18 kV (contact)
  - IEC61000-4-4 (EFT): 40 A (5/50 ns)
  - IEC61000-4-5 (surge): 1 A (8/20 µs)
- Bi-directional, working voltage up to V_{RWM} = ±24 V
- Low capacitance: C_L = 2.5 pF (typical)
- Very low reverse current. I_R = < 1nA (typical)
- Pb-free (RoHS compliant) and halogen free package

1.2 Application Examples

- ESD protection of USB-battery charger interface
- LCD Backlight protection
- NFC antenna protection
- Protection of high speed bus rated up to ±24 V

2 Product Description

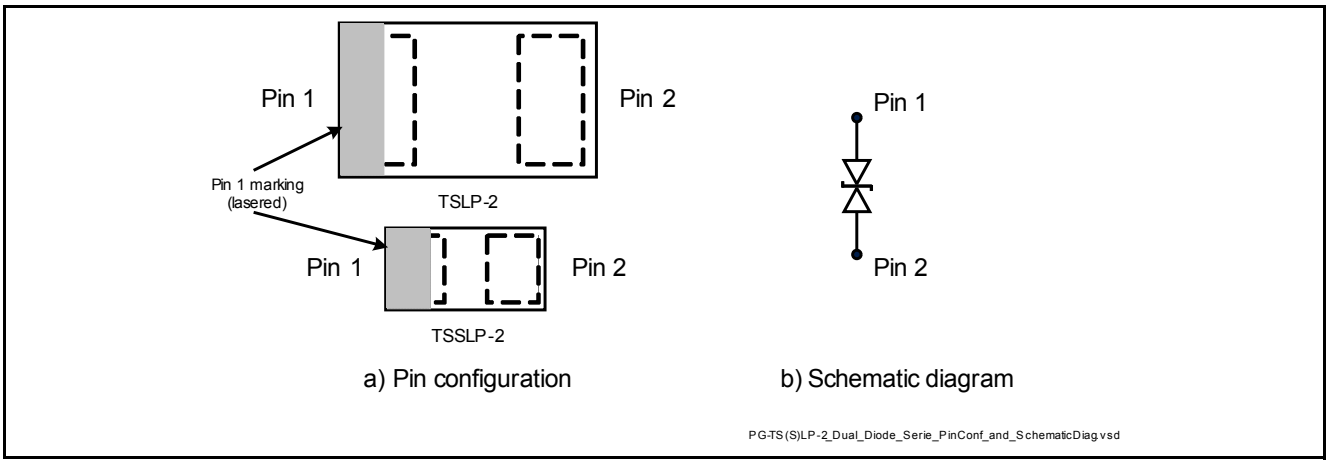

Figure 2-1 Pin Configuration and Schematic Diagram

Table 2-1 Ordering Information

Type	Package	Configuration	Marking code
ESD24VL1B-02LS	PG-TSSLP-2-1	1 line, bi-directional	n
ESD24VL1B-02LRH	PG-TSLP-2-17	1 line, bi-directional	n

3 Characteristics

Table 3-1 Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
ESD air discharge[1)] ESD contact discharge[1)]	V_{ESD}	-20 -18	– –	20 18	kV
Peak pulse current (t_p = 8/20 µs)[2)]	I_{PP}	-1	–	1	A
Operating temperature range	T_{OP}	-55	–	150	°C
Storage temperature	T_{stg}	-65	–	150	°C

1) V_{ESD} according to IEC61000-4-2

2) I_{PP} according to IEC61000-4-5

3.1 Electrical Characteristics at T_A = 25 °C, unless otherwise specified

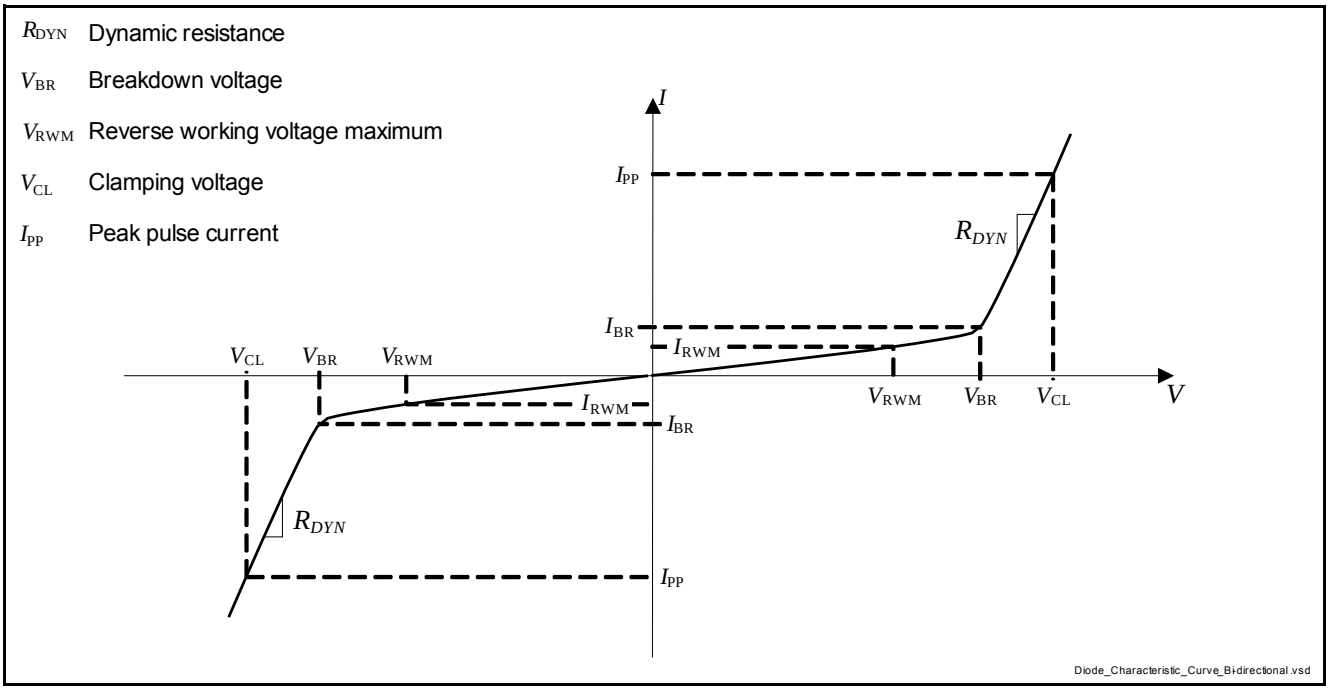

Figure 3-1 Definitions of electrical characteristics

Table 3-2 DC Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Reverse working voltage	V_{RWM}	-24	–	24	V	
Breakdown voltage	V_{BR}	24.3	25	–		I_R = 1 mA
Reverse current	I_R	–	<1	50	nA	V_R = 24 V

Table 3-3 RF Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Line capacitance	C_L	–	2.5	3.5	pF	V_R = 0 V, f = 1 MHz

Table 3-4 ESD Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clamping voltage[1)]	V_{CL}	–	55	–	V	I_{PP} = 16 A
Dynamic resistance[1)]	R_{DYN}	–	1.0	–	Ω	

1)Please refer to Application Note AN210[1] . TLP parameter: Z_0 = 50 Ω , t_p = 100ns, t_r = 300ps, averaging window: t_1 = 30 ns to t_2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP charactertistics between I_{PP1} = 10 A and I_{PP2} = 40 A.

3.2 Typical Characteristics at T_A=25°C, unless otherwise specified

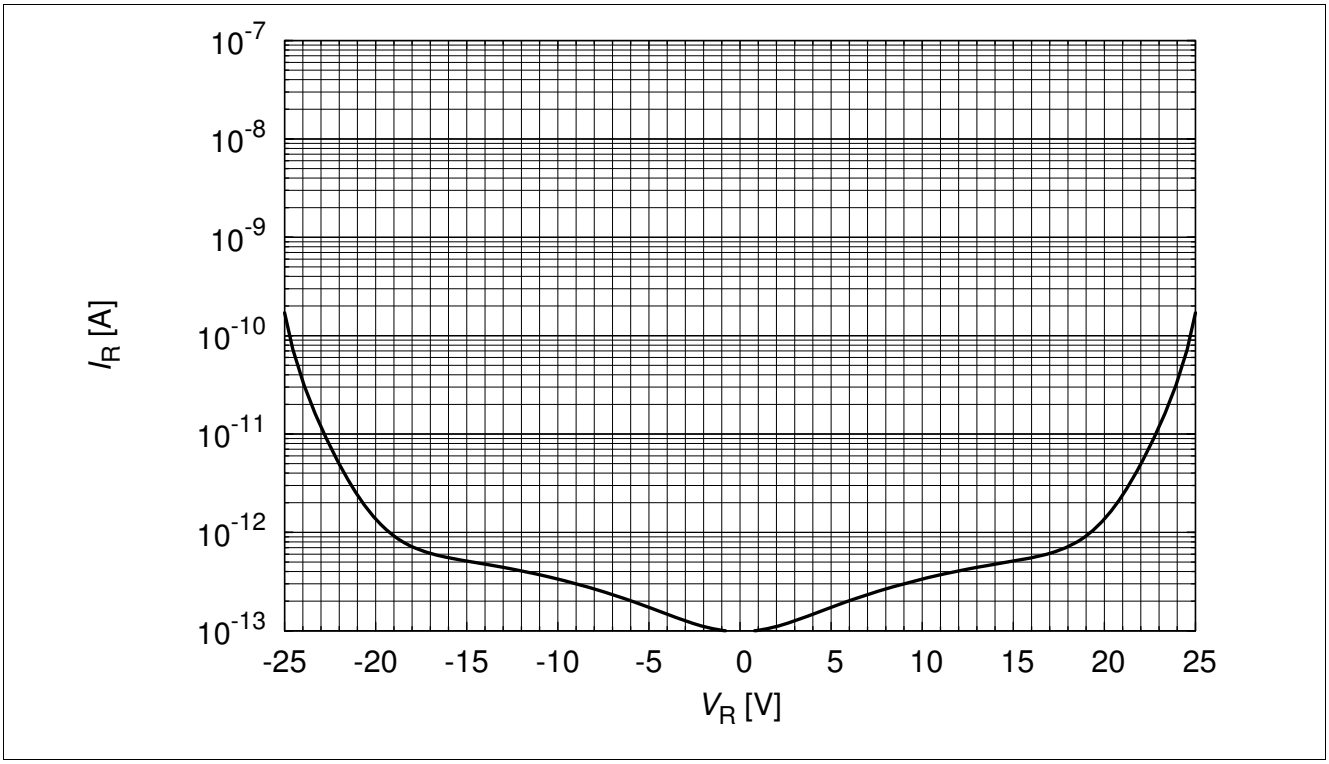

Figure 3-2 Reverse current: $I_R = f(V_R)$

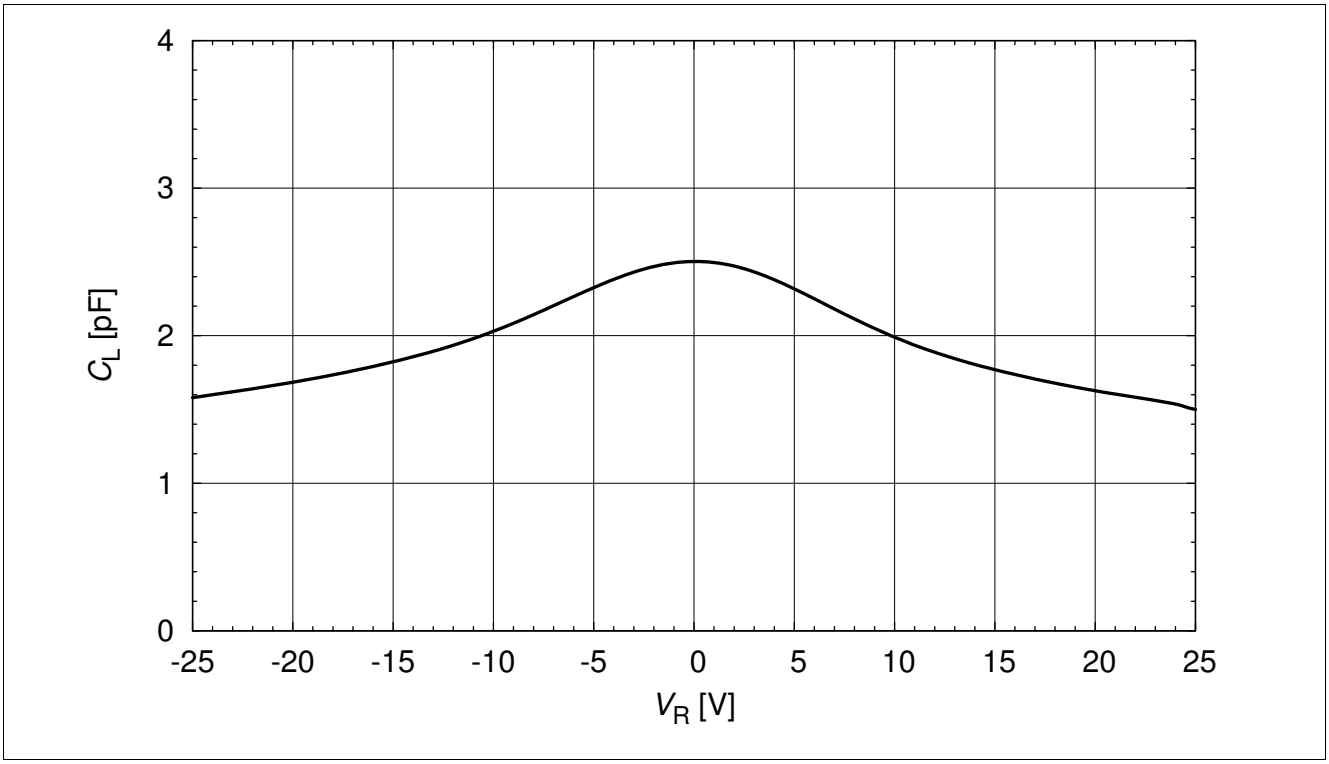

Figure 3-3 Line capacitance: $C_L = f(V_R)$, f = 1MHz

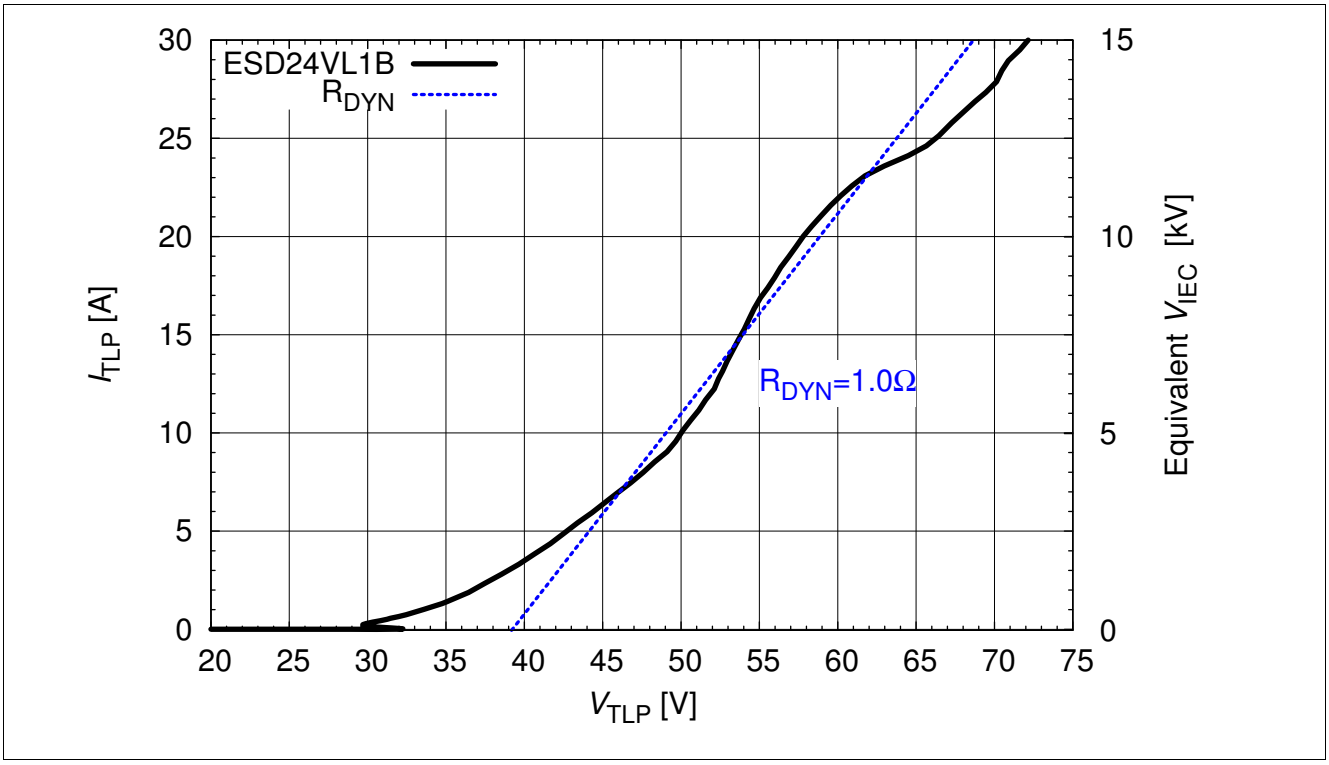

Figure 3-4 Clamping voltage (TLP): $I_{TLP} = f(V_{TLP})$[1]

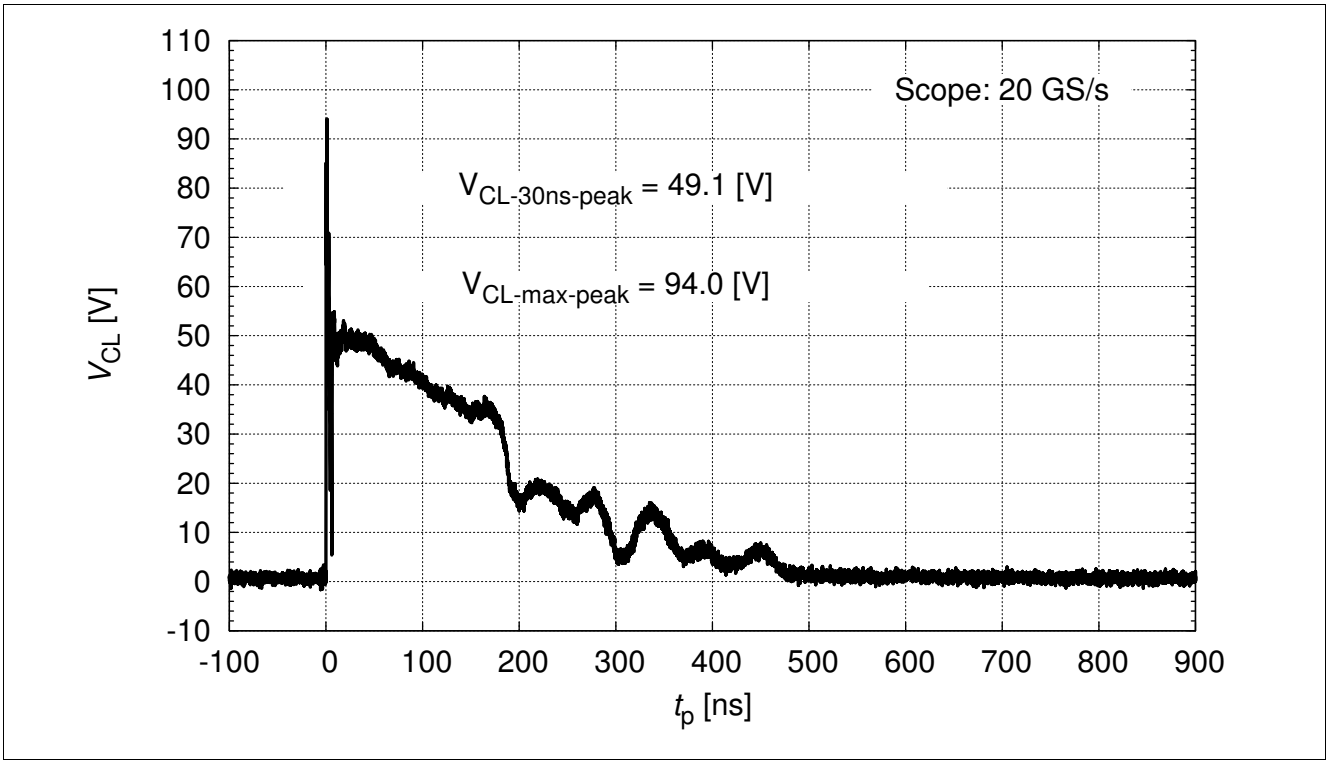

Figure 3-5 IEC61000-4-2 : $V_{CL} = f(t)$, 8 kV positive pulse from pin 1 to pin 2

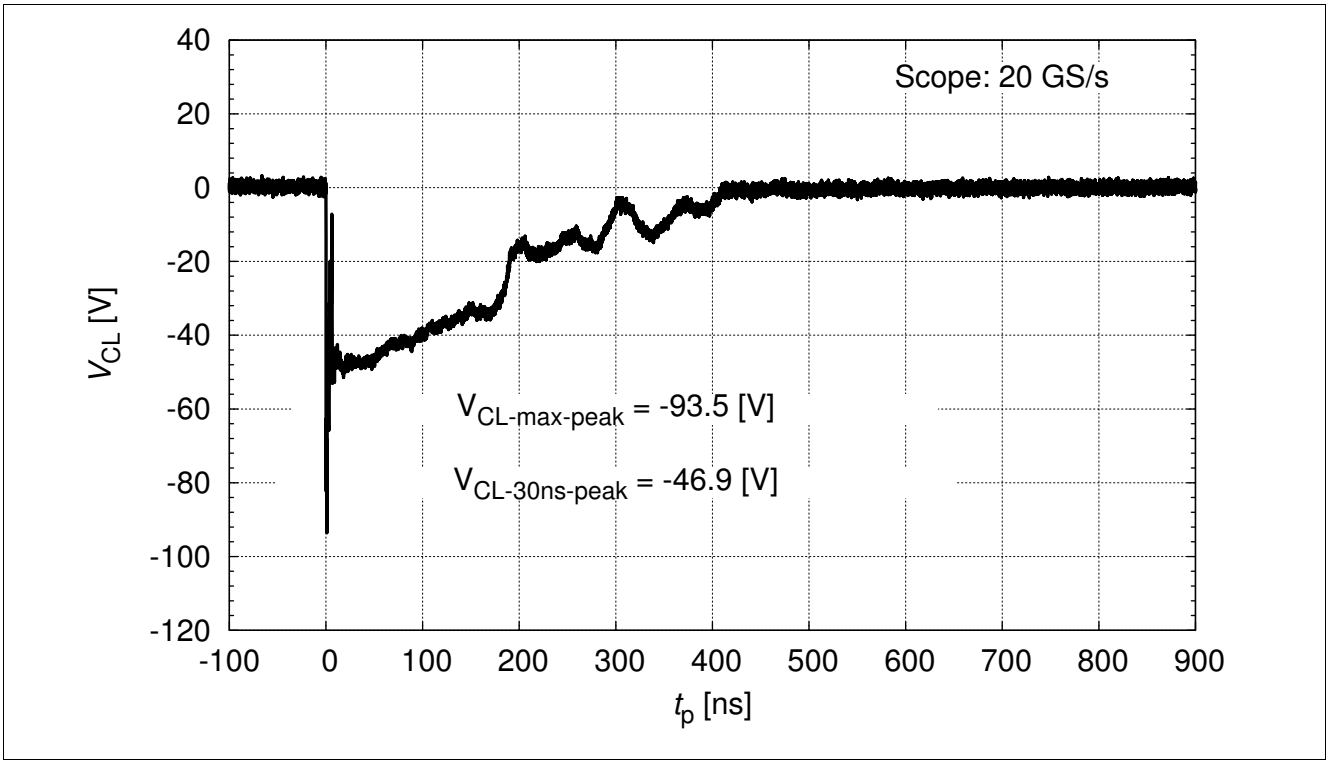

Figure 3-6 IEC61000-4-2 : $V_{CL} = f(t)$, 8 kV negative pulse from pin 1 to pin 2

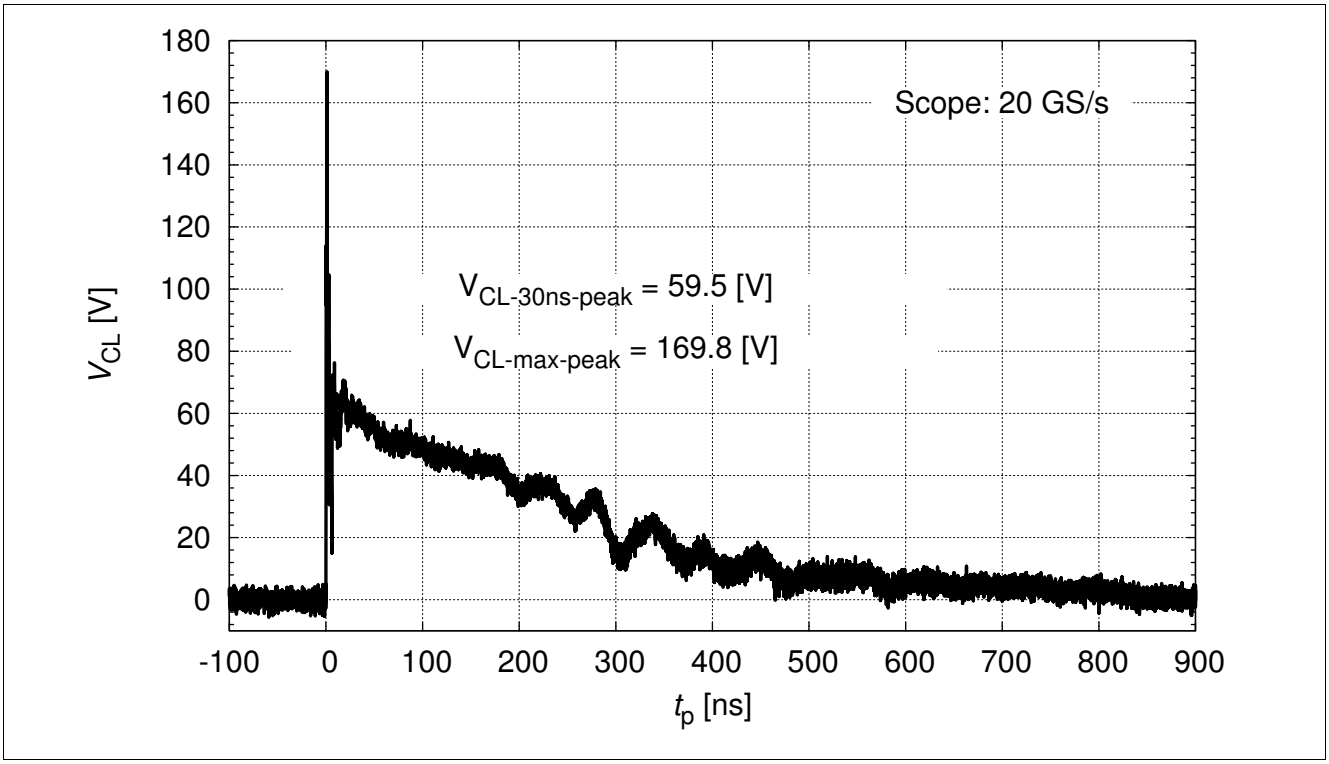

Figure 3-7 IEC61000-4-2 : V_{CL} = $f(t)$, 15 kV positive pulse from pin 1 to pin 2

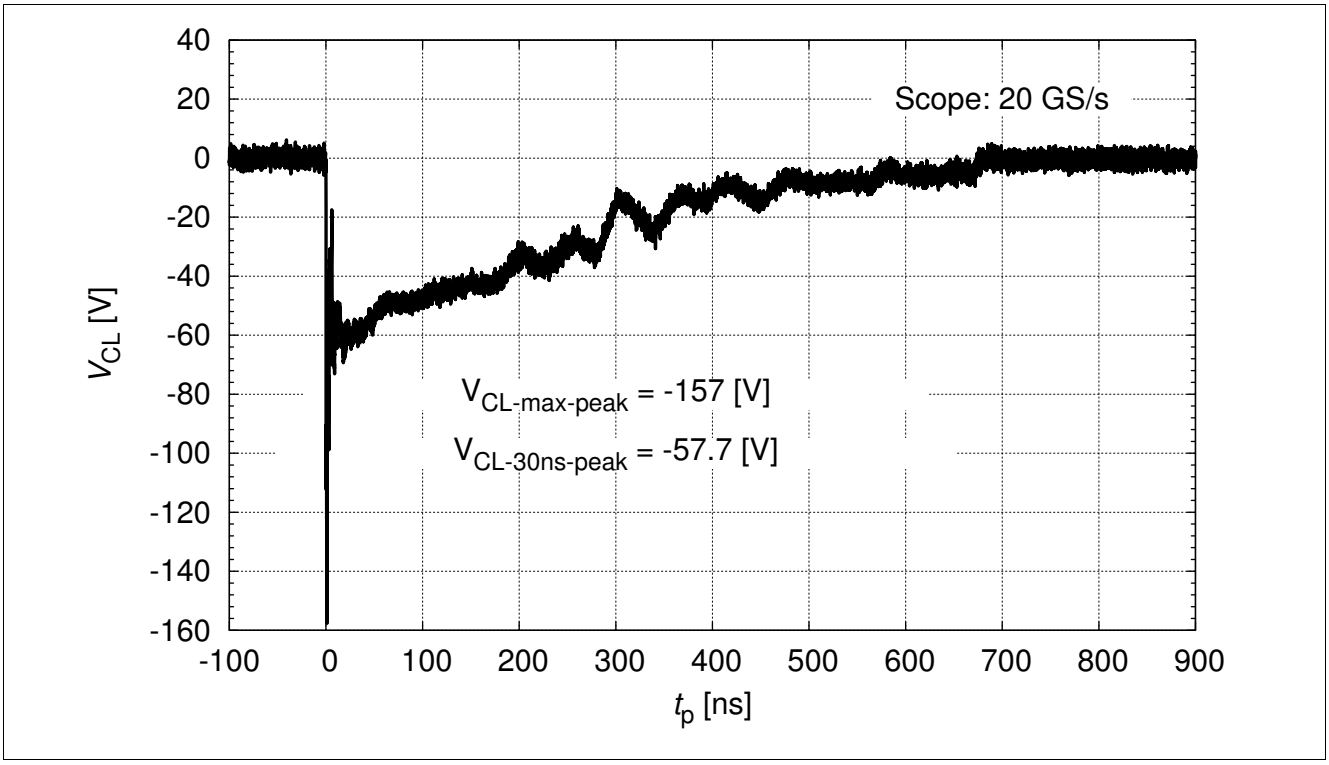

Figure 3-8 IEC61000-4-2 : V_{CL} = $f(t)$, 15 kV negative pulse from pin 1 to pin 2

4 Application Information

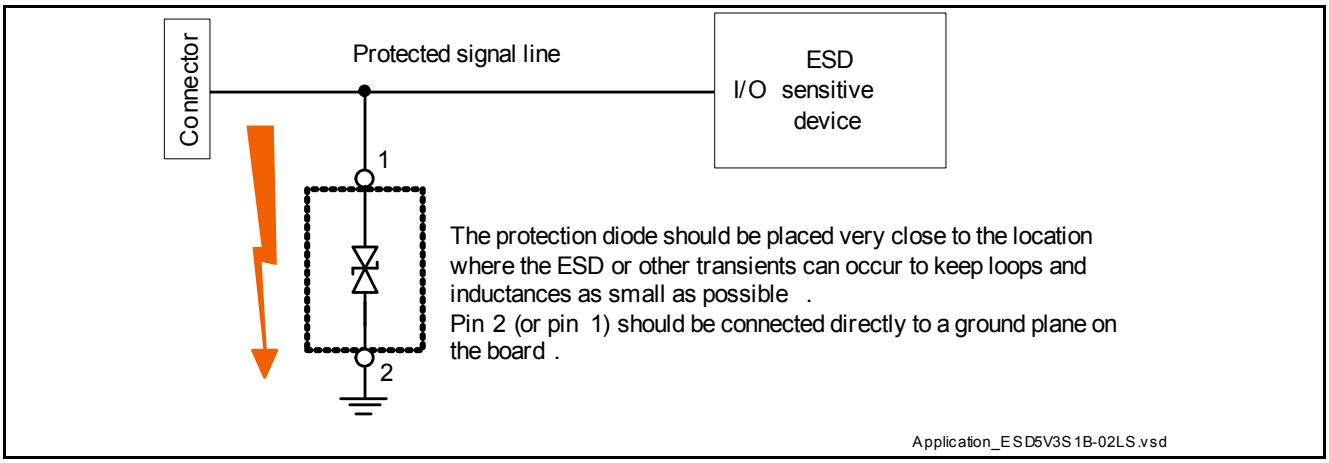

Figure 4-1 Single line, bi-directional ESD / Transient protection

5 Ordering Information Scheme (Examples)

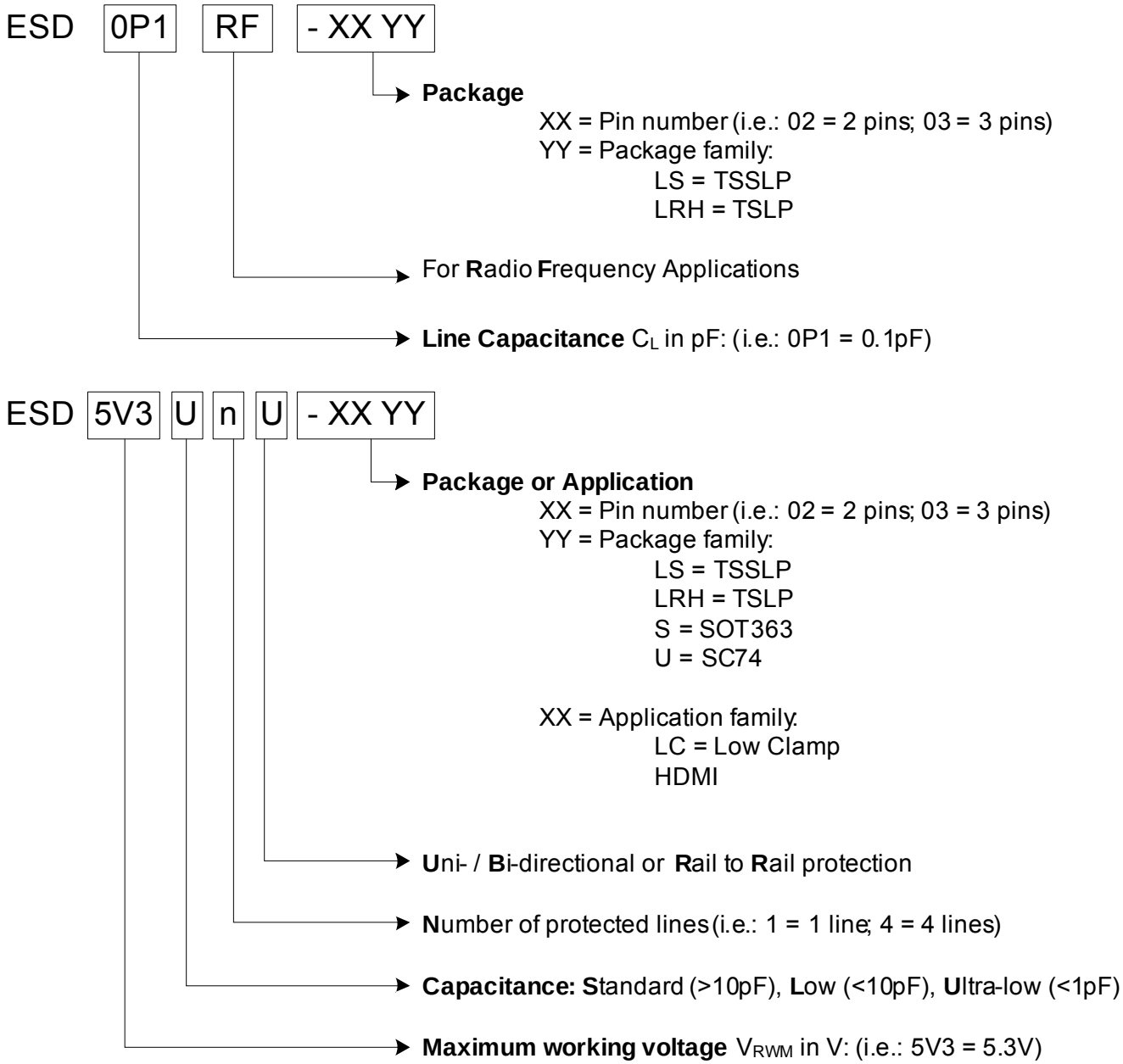

Figure 5-1 Ordering information scheme

6 Package Information

6.1 PG-TSLP-2-17 (mm) [2]

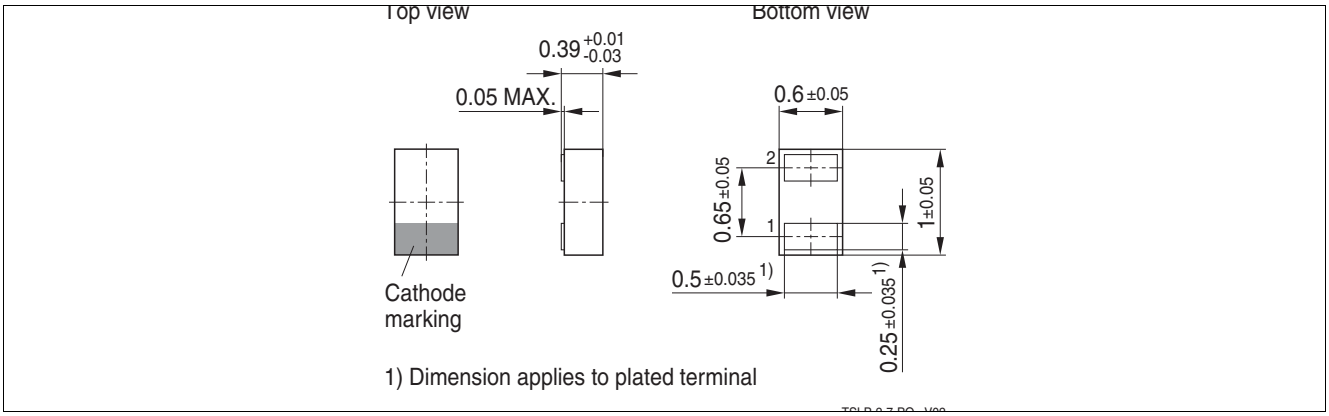

Figure 6-1 PG-TSLP-2-17: Package overview

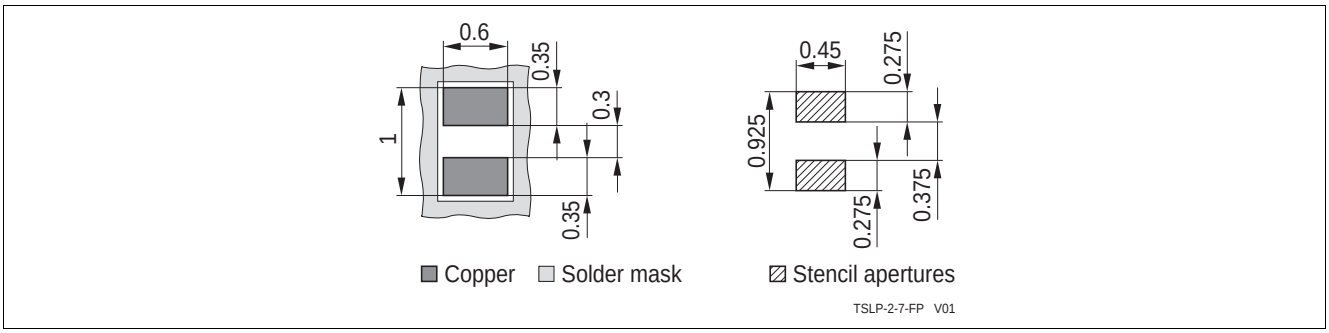

Figure 6-2 PG-TSLP-2-17: Footprint

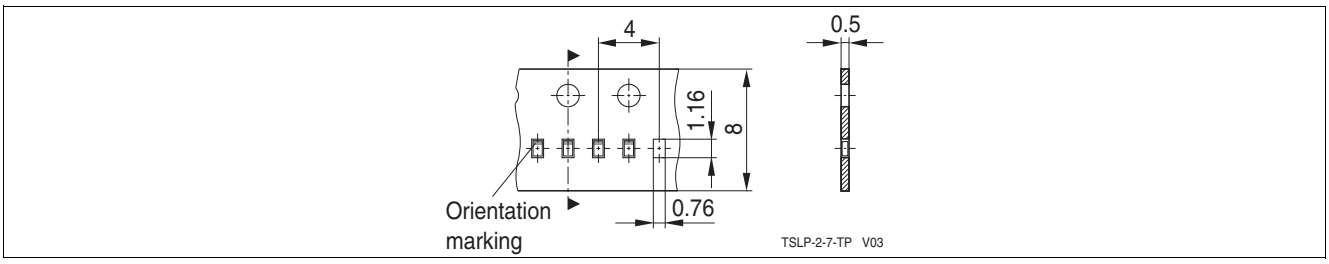

Figure 6-3 PG-TSLP-2-17: Packing

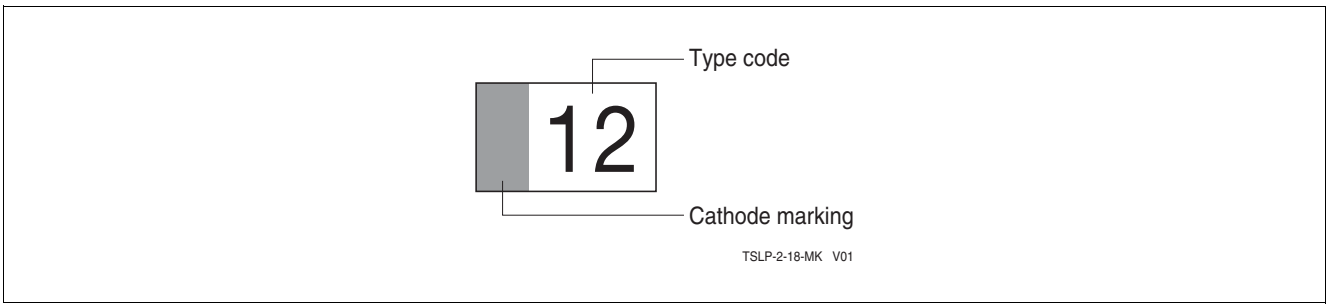

Figure 6-4 PG-TSLP-2-17: Marking (example)

6.2 PG-TSSLP-2-1 (mm) [2]

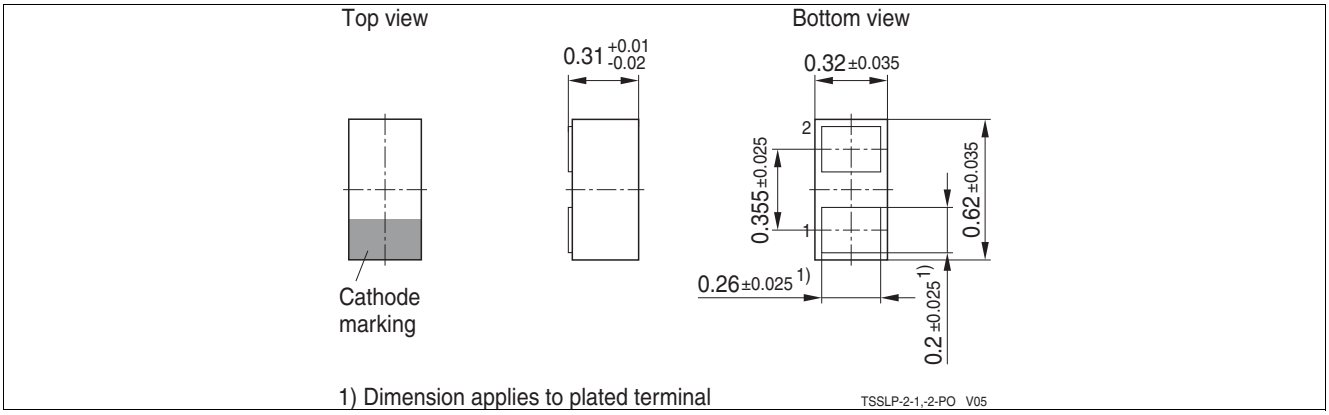

Figure 6-5 PG-TSSLP-2-1: Package overview

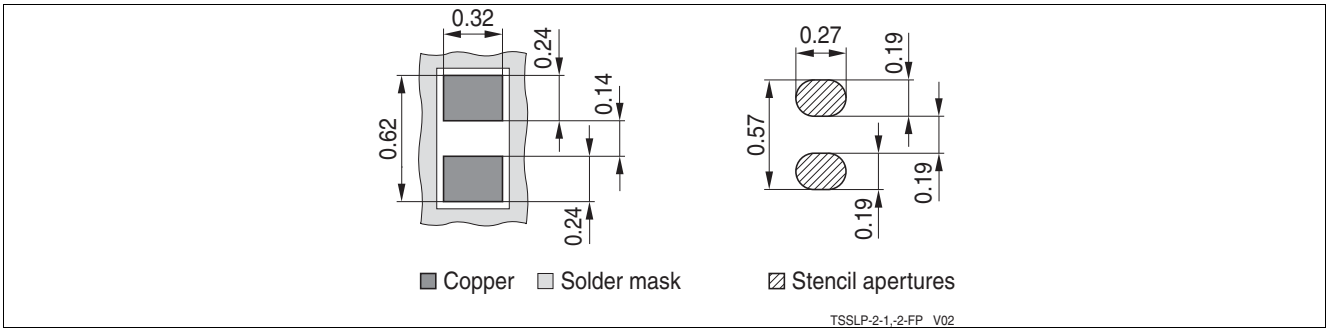

Figure 6-6 PG-TSSLP-2-1: Footprint

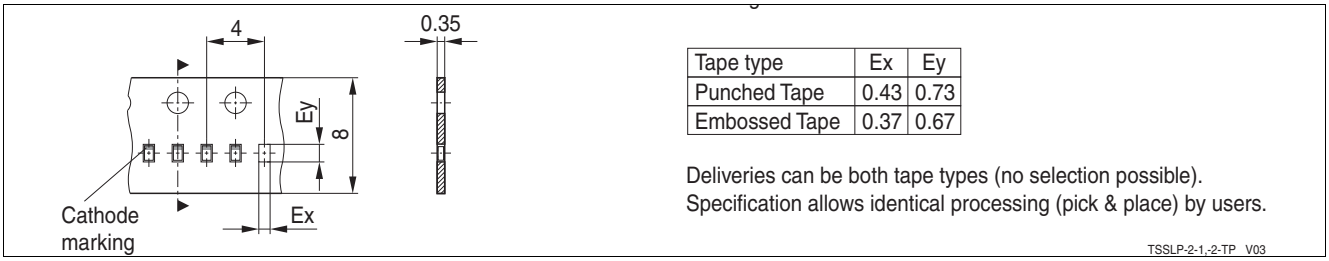

Figure 6-7 PG-TSSLP-2-1: Packing

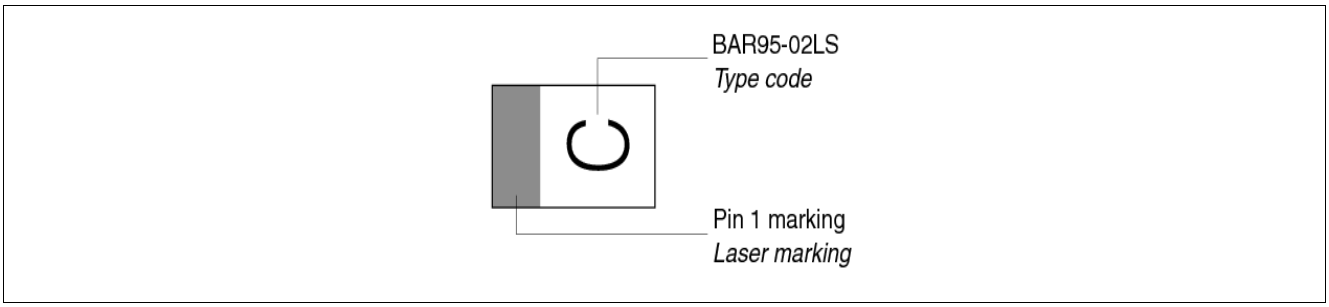

Figure 6-8 PG-TSSLP-2-1: Marking (example)

References

[1] Infineon AG - **Application Note AN210:** Effective ESD Protection design at System Level Using VF-TLP Characterization Methodology

[2] Infineon AG - Recommendations for PCB Assembly of Infineon TSLP and TSSLP Packages

Terminology

C_L	Line capacitance
DSC	Digital Still Camera
EFT	Electrical Fast Transient
ESD	Electrostatic Discharge
I_{PP}	Peak pulse current
I_R	Reverse current
LCD	Liquid Crystal Display
$\boldsymbol{P_{PK}}$	Peak pulse power
R_{DYN}	Dynamic resistance
RoHs	Restriction of Hazardous Substance directive
STB	Set-Top-Box
T_A	Ambient temperature
T_{OP}	Operation temperature
t_p	Pulse duration
T_{stg}	Storage temperature
V_{BR}	Breakdown voltage
V_{CL}	Reverse clamping voltage
V_{ESD}	Electrostatic discharge voltage
V_R	Reverse voltage
V_{RWM}	Reverse working voltage maximum

Predefined Names

Name	Initial Cross-Reference
X-GOLD	**X-GOLD**
XMM	**XMM**

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2. *New definitions must be inserted in a new row. Never change existing definitions, as they might be used in other documents.*
3. *This file does not need to be included in your book, but it must be in the fm sub-folder of your document.*
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